



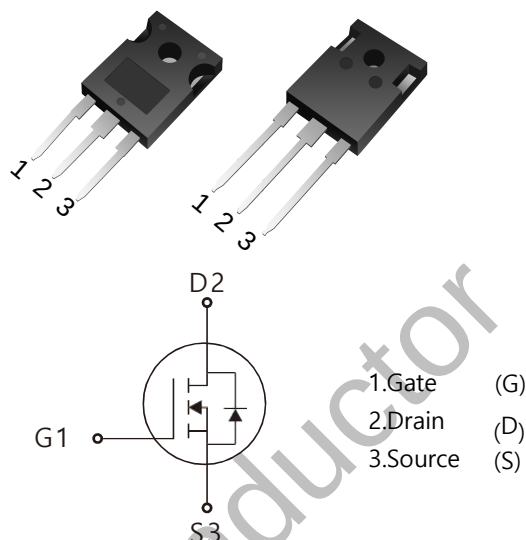
WGA65R041W

## Features:

- ☐ Super Junction technology
- ☐ Much lower  $R_{on} \cdot A$  Performance for On-state efficiency
- ☐ Better efficiency due to very low FOM
- ☐ Ultra Low Gate Charge:  $Q_g = 172\text{nC}$  (Typ.)
- ☐  $V_{DS} = 650\text{V}$ ,  $I_D = 62\text{A}$
- ☐  $R_{ds(on)}: 34\text{m}\Omega$  (Typ.) @  $V_G = 10\text{V}$
- ☐ 100% Avalanche Tested

TO-247S

TO-247

Maximum Ratings ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

| Symbol         | Parameter                                                        | Value       | Units            |
|----------------|------------------------------------------------------------------|-------------|------------------|
| $V_{DS}$       | Drain-Source Voltage                                             | 650         | V                |
| $I_D$          | Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ ) (Note 1) | 62          | A                |
|                | Drain Current -Continuous ( $T_C = 100^\circ\text{C}$ ) (Note 1) | 39          | A                |
| $I_{DM}$       | Drain Current - Pulsed (Note 1,2)                                | 248         | A                |
| $V_{GS}$       | Gate-Source Voltage                                              | $\pm 30$    | V                |
| $E_{AS}$       | Single Pulsed Avalanche Energy (Note 3)                          | 1656        | mJ               |
| $dV/dT$        | MOSFET $dV/dt$ ruggedness                                        | 40          | V/ns             |
|                | Reverse diode $dV/dt$                                            | 40          | V/ns             |
| $dI/dT$        | Maximum diode commutation current                                | 800         | A/ $\mu\text{s}$ |
| $P_D$          | Power Dissipation ( $T_C = 25^\circ\text{C}$ )                   | 416         | W                |
| $T_J, T_{STG}$ | Operating and Storage Temperature Range                          | -55 to +150 | $^\circ\text{C}$ |

## Thermal Characteristics

| Symbol          | Parameter                                                     | Value | Units              |
|-----------------|---------------------------------------------------------------|-------|--------------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case, Steady-State            | 0.3   | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient Steady State (Note 4) | 35    | $^\circ\text{C/W}$ |

**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$  unless otherwise noted)

| Symbol                                                 | Parameter                                     | Test Conditions                                                                                  | Min | Typ  | Max   | Units |
|--------------------------------------------------------|-----------------------------------------------|--------------------------------------------------------------------------------------------------|-----|------|-------|-------|
| Static Characteristics                                 |                                               |                                                                                                  |     |      |       |       |
| BV <sub>DSS</sub>                                      | Drain-Source Breakdown Voltage                | V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA                                                     | 650 |      |       | V     |
| I <sub>DSS</sub>                                       | Zero Gate Voltage Drain Current               | V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 25°C                            |     |      | 3.5   | μA    |
|                                                        |                                               | V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150°C                           |     | 1000 |       |       |
| I <sub>GSS</sub>                                       | Gate Leakage Current                          | V <sub>GS</sub> = ± 30 V, V <sub>DS</sub> = 0 V                                                  |     |      | ± 100 | nA    |
| V <sub>GS(TH)</sub>                                    | Gate Threshold voltage                        | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 3.3 mA                                      | 3   | 4    | 4.5   | V     |
| R <sub>DS(ON)</sub>                                    | Drain-Source on-state resistance              | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 33.1 A                                                  |     | 34   | 41    | mΩ    |
| G <sub>FS</sub>                                        | Forward Transconductance                      | V <sub>DS</sub> = 5 V, I <sub>D</sub> = 25 A                                                     |     | 40   |       | S     |
| Dynamic Characteristics                                |                                               |                                                                                                  |     |      |       |       |
| C <sub>ISS</sub>                                       | Input capacitance                             | V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, F = 1 MHz                                        |     | 6715 |       | pF    |
| C <sub>OSS</sub>                                       | Output capacitance                            |                                                                                                  |     | 245  |       | pF    |
| C <sub>RSS</sub>                                       | Reverse capacitance                           |                                                                                                  |     | 1.64 |       | pF    |
| R <sub>G</sub>                                         | Gate resistance                               | F = 1 MHz                                                                                        |     | 1.8  |       | Ω     |
| Switching Characteristics                              |                                               |                                                                                                  |     |      |       |       |
| T <sub>D(ON)</sub>                                     | Turn On Delay Time                            | V <sub>DS</sub> = 400 V, I <sub>D</sub> = 40 A, V <sub>GS</sub> = 10 V, R <sub>GEN</sub> = 2.2 Ω |     | 28   |       | ns    |
| T <sub>R</sub>                                         | Rise Time                                     |                                                                                                  |     | 44   |       | ns    |
| T <sub>D(OFF)</sub>                                    | Turn Off Delay Time                           |                                                                                                  |     | 106  |       | ns    |
| T <sub>F</sub>                                         | Fall Time                                     |                                                                                                  |     | 42   |       | ns    |
| Q <sub>G</sub>                                         | Total Gate Charge                             | V <sub>DS</sub> = 480 V, I <sub>D</sub> = 49.6 A, V <sub>GS</sub> = 10 V                         |     | 172  |       | nC    |
| Q <sub>GS</sub>                                        | Gate-Source Charge                            |                                                                                                  |     | 40   |       | nC    |
| Q <sub>GD</sub>                                        | Gate-Drain Charge                             |                                                                                                  |     | 83   |       | nC    |
| Drain-Source Diode Characteristics and Maximum Ratings |                                               |                                                                                                  |     |      |       |       |
| I <sub>S</sub>                                         | Maximum Continuous Body-Diode Forward Current |                                                                                                  |     |      | 62    | A     |
| I <sub>SM</sub>                                        | Maximum Pulsed Body-Diode Forward Current     |                                                                                                  |     |      | 248   | A     |
| V <sub>SD</sub>                                        | Diode Forward Voltage                         | V <sub>GS</sub> = 0 V, I <sub>S</sub> = 49.6 A                                                   |     | 0.92 |       | V     |
| Q <sub>RR</sub>                                        | Reverse recovery charge                       | V <sub>DS</sub> = 400V, I <sub>D</sub> = 49.6A di/dt = 100A/μS                                   |     | 1291 |       | nC    |
| T <sub>RR</sub>                                        | Reverse recovery time                         |                                                                                                  |     | 177  |       | ns    |
| I <sub>RRM</sub>                                       | Peak Reverse Recovery Current                 |                                                                                                  |     | 13.7 |       | A     |

**Notes:**

1. The max drain current rating limited by package and maximum junction temperature
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3.  $L = 23\text{ mH}$ ,  $V_{DD} = 150\text{ V}$ ,  $I_{AS} = 12\text{ A}$ ,  $R_G = 25\text{ }\Omega$ . Starting  $T_J = 25^\circ\text{C}$ , guarantee by design
4. Mount on minimum PCB layout

## Typical Performance Characteristics

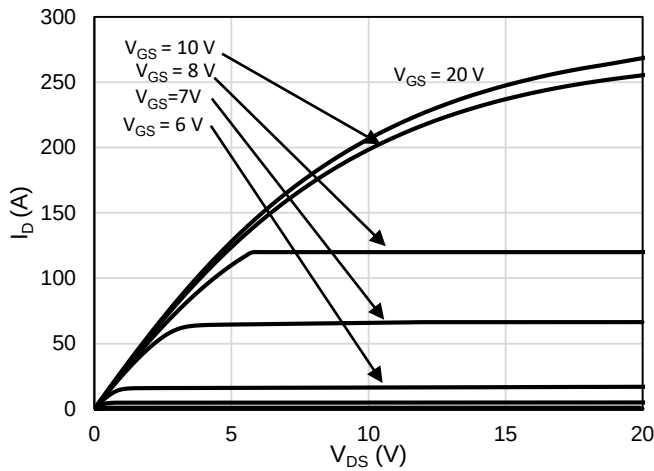


Figure 1: On-Region Characteristics

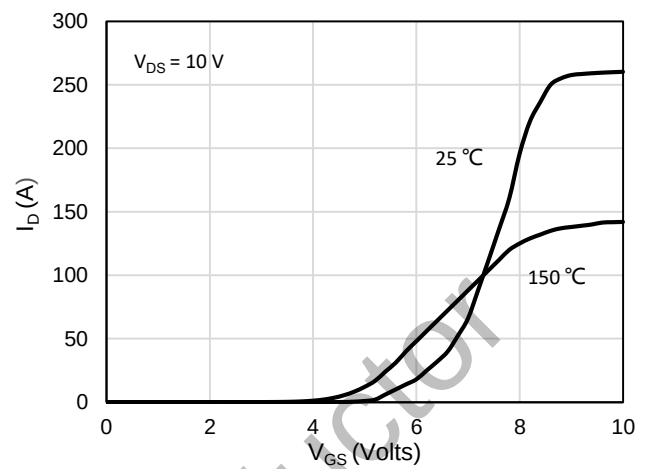


Figure 2: Transfer Characteristics

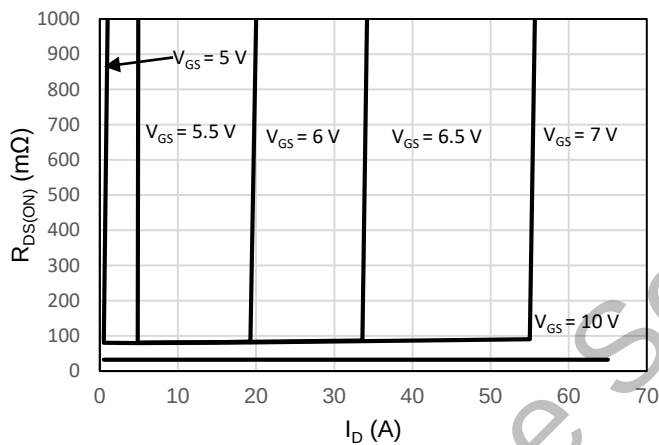


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

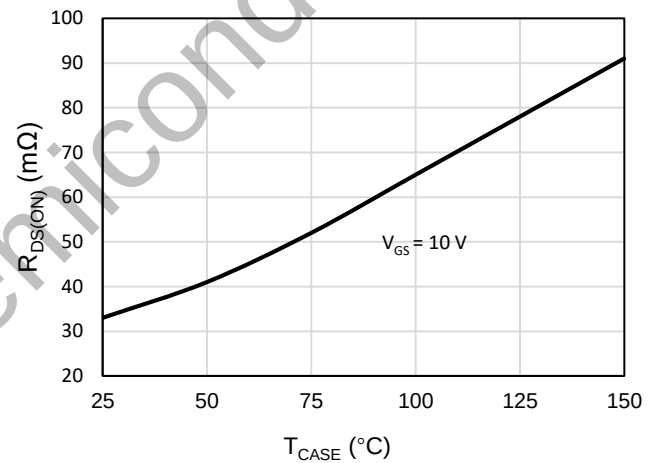
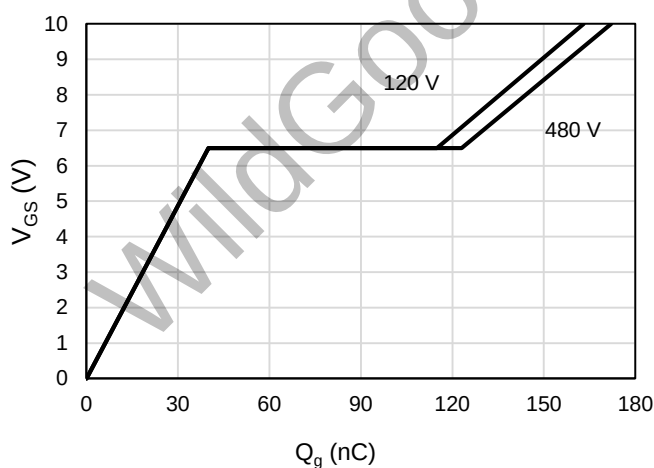
Figure 4: On-Resistance vs.  $T_{CASE}$ 

Figure 5: Gate-Charge Characteristics

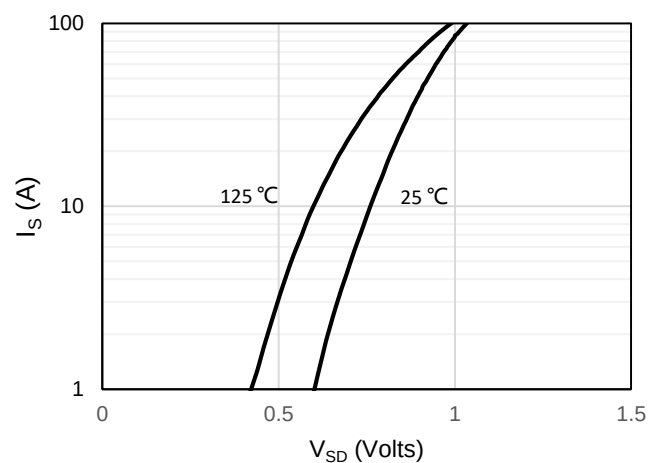


Figure 6: Body-Diode Characteristics

## Typical Performance Characteristics

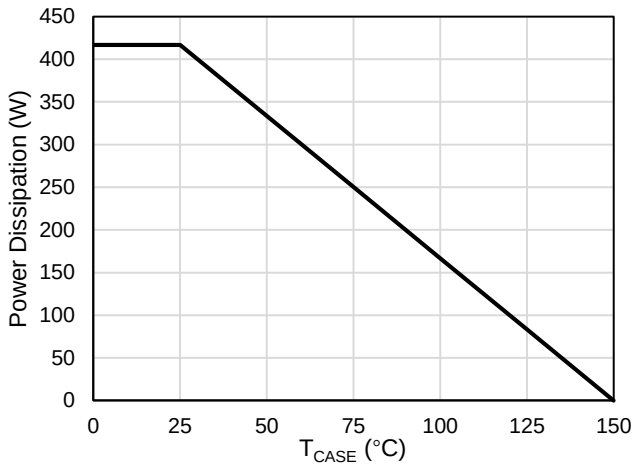


Figure 7: Power De-rating

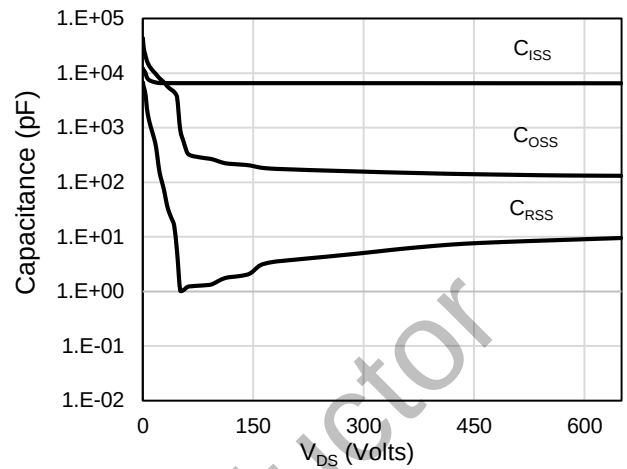


Figure 8: Capacitance Characteristics

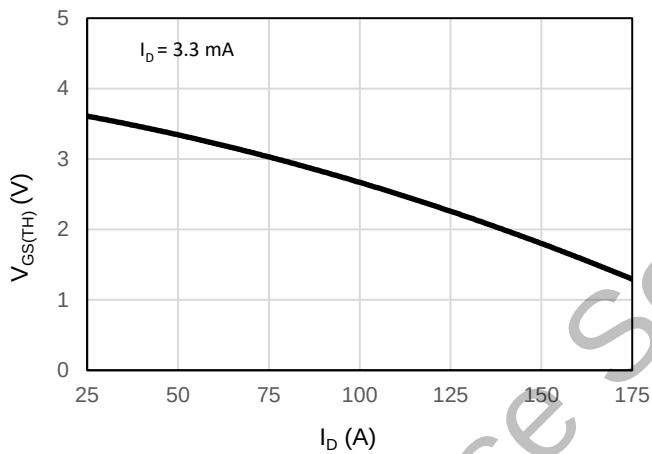
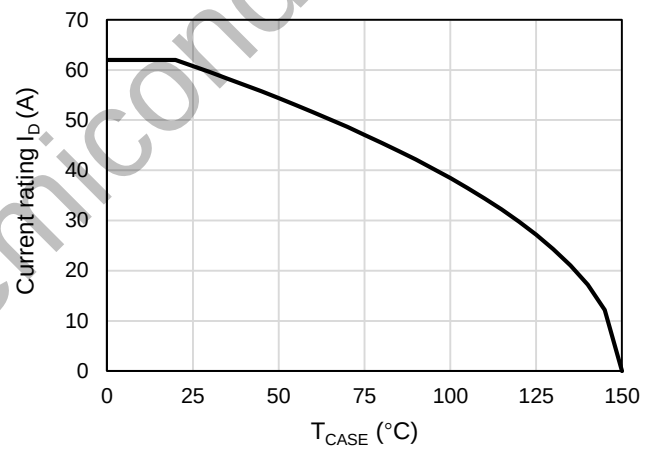
Figure 9:  $V_{GS(TH)}$  vs.  $T_{CASE}$ 

Figure 10: Current De-rating

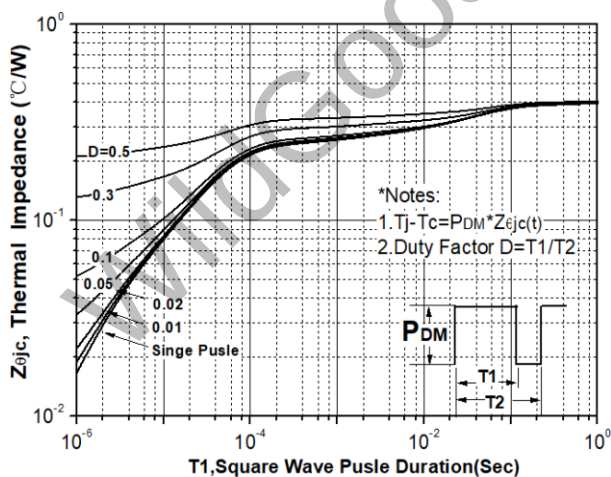


Figure 11: Transient Thermal Response Curve

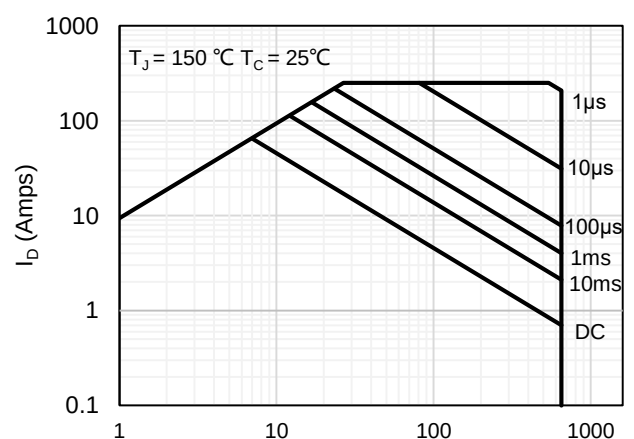
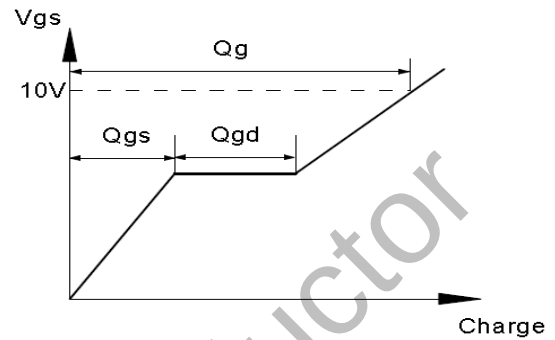
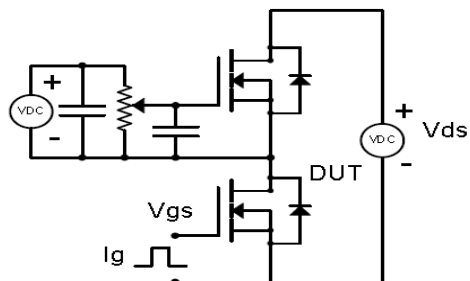


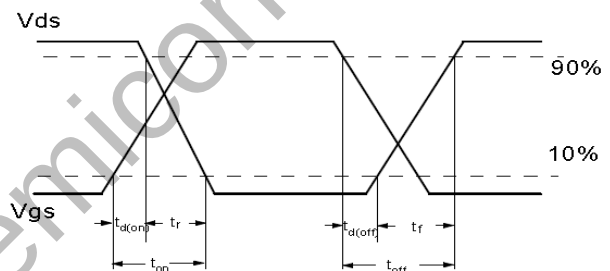
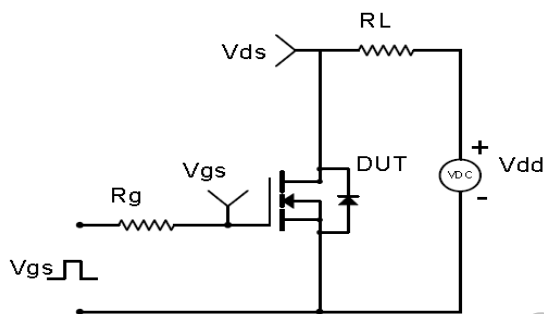
Figure 12: Maximum Forward Biased Safe Operating Area

## Test Circuit & Waveform

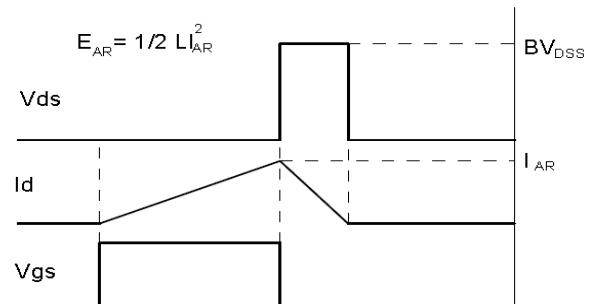
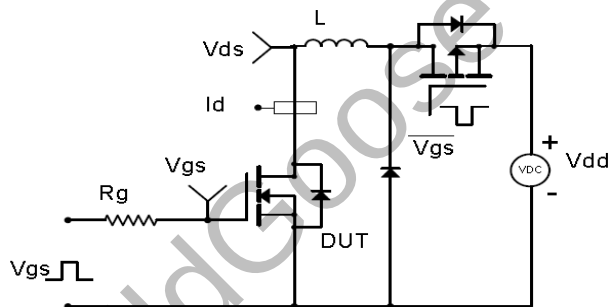
### Gate Charge Test Circuit & Waveform



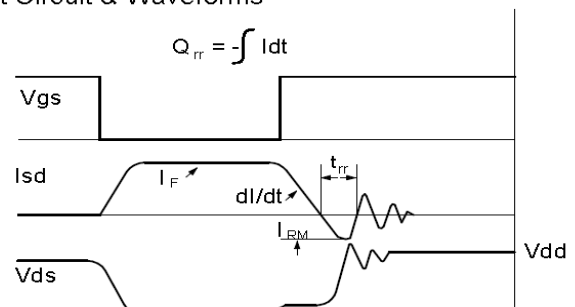
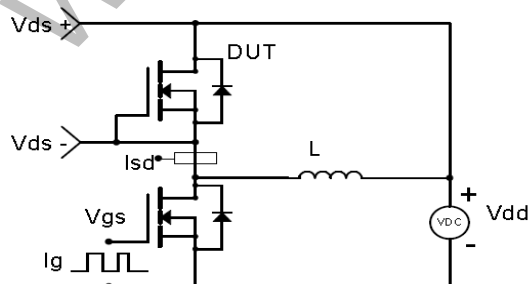
### Resistive Switching Test Circuit & Waveforms



### Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



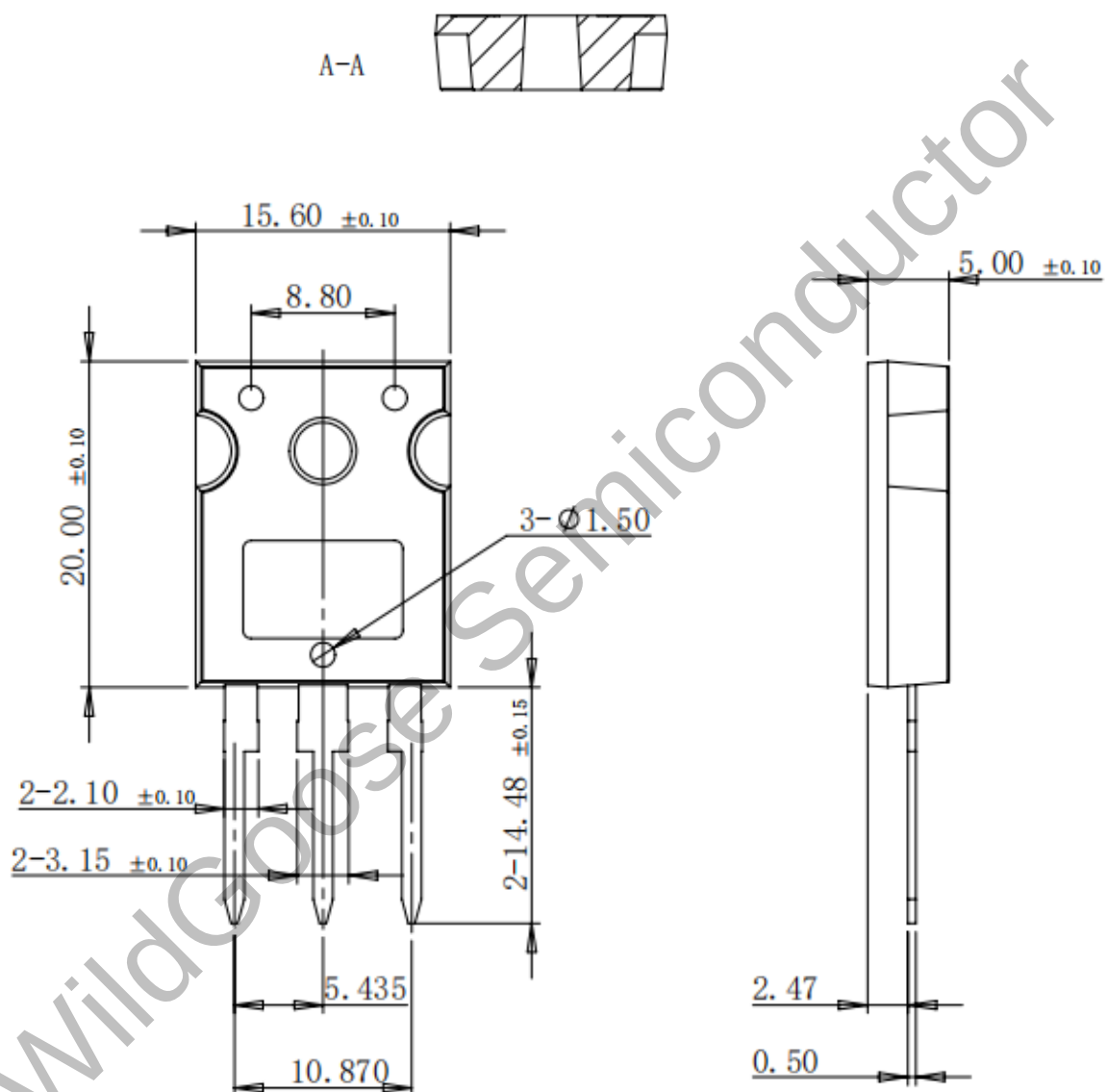
### Diode Recovery Test Circuit & Waveforms



Package Dimension

## TO-247S

Unit: mm



Package Dimension

## TO-247

Unit: mm

